(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
18 March 2010 (18.03.2010)

PCT

(10) International Publication Number
WO 2010/030052 A1

(51) International Patent Classification:
H01L 21/60 (2006.01)

(21) International Application Number:
PCT/KR2008/006008

(22) International Filing Date:
13 October 2008 (13.10.2008)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:
10-2008-0090518
12 September 2008 (12.09.2008) KR

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(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

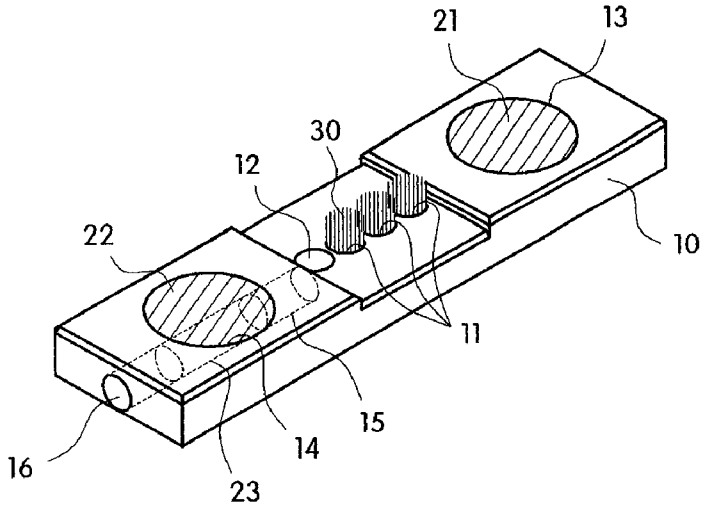
(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, NO, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report (Art. 21(3))*

(54) **Title**: CLEANING JIG OF CAPILLARY FOR WIRE BONDING, CLEANING DEVICE OF CAPILLARY FOR WIRE BONDING, METHOD FOR FABRICATING THEREOF AND METHOD FOR CLEANING USING THE SAME

【Figure 5】



(57) **Abstract**: The present invention relates to a cleaning jig of a capillary for wire bonding, a cleaning device of a capillary for wire bonding, a method for fabricating thereof, and a method for cleaning a capillary using the same, which can remove pollutants in the capillary without separating the capillary from a transducer at the time of performing the wire bonding work using the capillary for wire bonding.

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